BAS28

SURFACE MOUNT DUAL, ISOLATED HIGH SPEED SILICON SWITCHING DIODES



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR BAS28 consists of two electrically isolated ultra-high speed silicon switching diodes manufactured by the epitaxial planar process and packaged in an epoxy molded SOT-143 surface mount case. This device is designed for high speed switching applications.

MARKING CODE: A61 or JTW



MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	75	V
Peak Repetitive Reverse Voltage	V _{RRM}	85	V
Continuous Forward Current	I _F	250	mA
Peak Repetitive Forward Current	I _{FRM}	500	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0ms	I _{FSM}	2.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ.ΙΔ	357	°C/W

ELECTRICAL	CHARACTERISTICS PER	DIODE: (TA=25°C unless	otherwise noted)

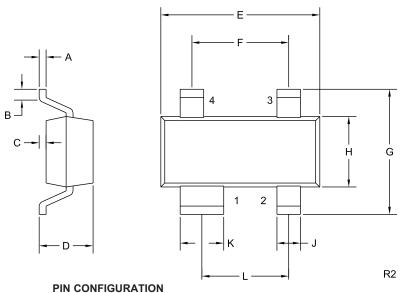
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =25V, T _A =150°C		30	μΑ
I_{R}	V _R =75V		1.0	μΑ
I_R	V _R =75V, T _A =150°C		50	μΑ
V_{F}	I _F =1.0mA		715	mV
V_{F}	I _F =10mA		855	mV
VF	I _F =50mA		1.00	V
V_{F}	I _F =150mA		1.25	V
C_T	$V_R=0$, f=1.0MHz		2.0	pF
t _{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω		6.0	ns
Q_S	I_F =10mA, V_R =5.0V, R_L =500 Ω		45	рС
V_{FR}	I _F =10mA, t _r =20ns		1.75	V

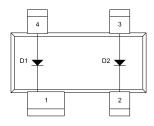
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SOT-143 CASE - MECHANICAL OUTLINE





LEAD CODE:

- 1) CATHODE D1
- 2) CATHODE D2
- 3) ANODE D2
- 4) ANODE D1

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DIMENSIONS					
	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	
Α	0.003	0.006	0.08	0.15	
В	0.006	-	0.15	-	
С	-	0.005	-	0.13	
D	-	0.045	-	1.14	
Е	0.110	0.120	2.79	3.04	
F	0.075		1.90		
G	-	0.098	-	2.50	
Н	0.047	0.055	1.19	1.40	
J	0.014	0.020	0.36	0.50	
K	0.030	0.037	0.76	0.93	
Ĺ	0.067		1.70		

SOT-143 (REV: R2)

R7 (20-October 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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